

ENGINEERING	PRODUCT SPECIFICATION	SPEC.NO.: SPCI1221
DEPT.	For CID1 Series Connector System	PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment
MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO: CID1 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

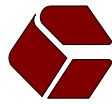
6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 0.6 mm (.024") ~ 1.2 mm (.047"),1.6mm(.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : David APPROVED : Eisley VERIFIED : Hank .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		(AWG#18 OD:0.80mm) 9.0A AC (r.m.s.)/DC 300V AC (r.m.s.)/DC
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1600 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Single contact withdrawal force	Measure force to withdrawal using diameter 0.80mm solid wire at speed 25± 3 mm per minute	2.0 Kgf min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions (MIL-STD-202,method 201A)	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solder ability	Lead-Free Process for SMT Type: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Refer Reflow temperature profile	No damage
9.4	Heat aging	85 ± 2°C , 96 hours(JIS C0021/MIL-STD-202,method 108A,condition A)	No damage Contact resistance: Less than twice of initial



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	ITEM	TEST CONDITION	REQUIREMENT
9.5	Humidity	60 ± 2°C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested (JIS C0020/MIL-STD-202, method 103 B, condition B)	Appearance: No damage Contact resistance: Less than twice of initial Insulation resistance: To pass Para 7-4
9.6	Temperature cycling	Five cycle consists of :(JIS C0025) (1)-55 ⁺⁰ / ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 85 ⁺³ / ₋₀ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35 ± 2°C Solution: 5 ± 1% Spray time: 48 ± 4 hours Measurement must be taken after water rinse(JIS C5028/MIL-STD-202, method 101 D, condition B)	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -35 to + 105°C

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Paste

